Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L24	4556	(HDP or HDPCvD or (high adj density adj plasma)) and (polish$6 or CMP) and (polysilicon or polySi or ((poly or polycrylline) near5 (Si or silicon)) or conductor or bitline or (bit adj line) or wiring or interconnect$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 12:46
L25	3975	24 and (stop$6 or etchstop or polishstop or mask or hardmask or endpoint or detect$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 12:48
L26	3896	25 and (IC or (integrated adj circuit) or semiconductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 12:48
L27	3810	26 and (@ad<="20040129" or @rlad<="20040129")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 12:49
L28	6284	(HDP or HDPCvD or (high adj density adj plasma)) same (oxide or SiO2 or SiO?sub$2 or dioxide or glass or silicate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 12:50
L29	2938	27 and 28	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 12:50